

# R1LV0208BSA

# 2Mb Advanced LPSRAM (256k word x 8bit)

R10DS0272EJ0101 Rev.1.01 2020.2.20

### **Description**

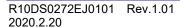
The R1LV0208BSA is a family of low voltage 2-Mbit static RAMs organized as 262,144-word by 8-bit, fabricated by Renesas's high-performance 0.15um CMOS and TFT technologies. The R1LV0208BSA has realized higher density, higher performance and low power consumption. The R1LV0208BSA is suitable for memory applications where a simple interfacing, battery operating and battery backup are the important design objectives. The R1LV0208BSA has been packaged in 32-pin sTSOP.

#### **Features**

- Single 2.7V~3.6V power supply
- Small stand-by current: 1µA (3.0V, typical)
- No clocks, No refresh
- All inputs and outputs are TTL compatible.
- Easy memory expansion by CS1# and CS2
- Common Data I/O
- Three-state outputs: OR-tie Capability
- OE# prevents data contention on the I/O bus

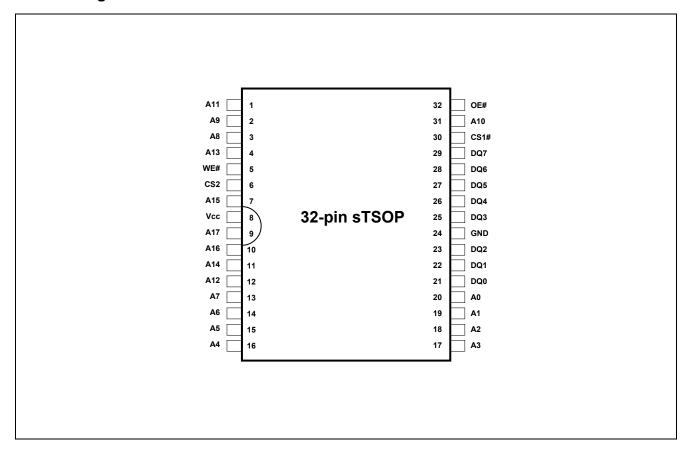
### **Ordering Information**

| Orderable part name | Access<br>time | Temperature range | Package           | Shipping container |
|---------------------|----------------|-------------------|-------------------|--------------------|
| R1LV0208BSA-5SI#B1  | FF             | 40 +05°C          | 8mm×13.4mm 32-pin | Tray               |
| R1LV0208BSA-5SI#S1  | 55 ns          | -40 ~ +85°C       | plastic sTSOP     | Embossed tape      |





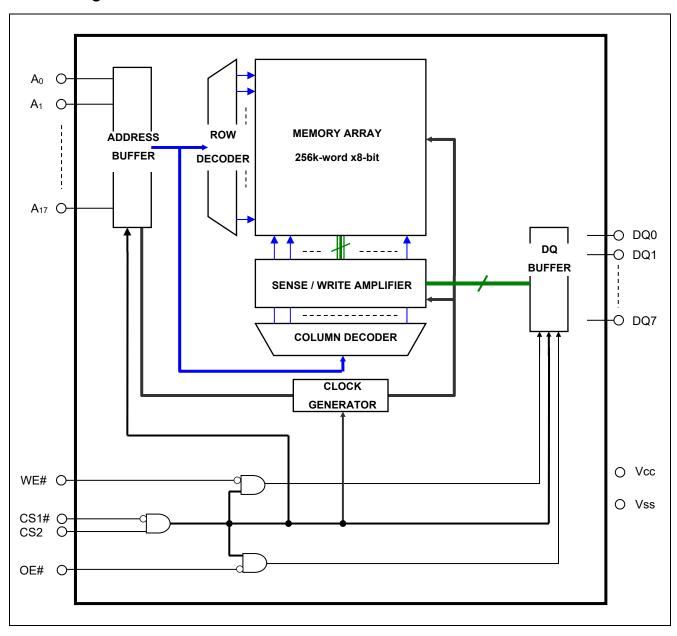
## **Pin Arrangement**



# **Pin Description**

| Pin name   | Function          |
|------------|-------------------|
| Vcc        | Power supply      |
| Vss (GND)  | Ground            |
| A0 to A17  | Address input     |
| DQ0 to DQ7 | Data input/output |
| CS1#       | Chip select 1     |
| CS2        | Chip select 2     |
| WE#        | Write enable      |
| OE#        | Output enable     |

## **Block Diagram**



# **Operation Table**

| CS1# | CS2 | WE# | OE# | DQ0~7  | Operation      |
|------|-----|-----|-----|--------|----------------|
| Х    | L   | Χ   | Χ   | High-Z | Stand-by       |
| Н    | Х   | Х   | Х   | High-Z | Stand-by       |
| L    | Н   | L   | Χ   | Din    | Write          |
| L    | Н   | Н   | L   | Dout   | Read           |
| L    | Н   | Н   | Н   | High-Z | Output disable |

Note 1. H: VIH L:VIL X: VIH or VIL

## **Absolute Maximum**

| Parameter                                   | Symbol | Value               | unit |
|---|--------|---------------------|------|
| Power supply voltage relative to Vss        | Vcc    | -0.5 to +4.6        | V    |
| Terminal voltage on any pin relative to Vss | VT     | -0.5*1 to Vcc+0.5*2 | V    |
| Power dissipation                           | PT     | 0.7                 | W    |
| Operation temperature                       | Topr   | -40 to +85          | °C   |
| Storage temperature range                   | Tstg   | -65 to 150          | °C   |
| Storage temperature range under bias        | Tbias  | -40 to +85          | °C   |

Note 1. –3.0V for pulse ≤ 30ns (full width at half maximum)

2. Maximum voltage is +4.6V.

## **DC Operating Conditions**

| Parameter                 | Symbol   | Min. | Тур. | Max.    | Unit | Note |
|---------------------------|----------|------|------|---------|------|------|
| Supply voltage            | Vcc      | 2.7  | 3.0  | 3.6     | V    |      |
|                           | Vss      | 0    | 0    | 0       | V    |      |
| Input high voltage        | ViH      | 2.0  | -    | Vcc+0.3 | V    |      |
| Input low voltage         | $V_{IL}$ | -0.3 | -    | 0.6     | V    | 1    |
| Ambient temperature range | Та       | -40  | -    | +85     | °C   |      |

Note 1. -3.0V for pulse  $\leq 30$ ns (full width at half maximum)

### **DC Characteristics**

| Parameter                 | Symbol           | Min.         | Тур.            | Max. | Unit | Test conditions   |   |  |  |
|---------------------------|------------------|--------------|-----------------|------|------|---|---|--|--|
| Input leakage current     | ILI              | -            | -               | 1    | μΑ   | Vin = Vss to Vcc  |   |  |  |
| Output leakage current    | <b>I</b> LO      | -            | -               | 1    | μА   | CS1# =V <sub>IH</sub><br>VI/O =Vss  | or CS2 =V <sub>IL</sub> or OE# =V <sub>IH</sub> ,<br>to Vcc   |  |  |
| Average operating current | Icc1             | -            | 15              | 25   | mA   |   | duty =100%, II/O = 0mA,<br>, CS2 =V <sub>IH</sub> , Others = V <sub>IH</sub> /V <sub>IL</sub>                               |  |  |
|                           | Icc2             | -            | 2               | 5    | mA   | Cycle =1µs, duty =100%, II/O = 0mA,<br>CS1# ≤ 0.2V, CS2 ≥ Vcc-0.2V,<br>V <sub>IH</sub> ≥ Vcc-0.2V, V <sub>IL</sub> ≤ 0.2V |   |  |  |
| Standby current           | lsв              | 1            | -               | 0.33 | mA   | , ,   | V <sub>IH</sub> , Others =V <sub>IH</sub> /V <sub>IL</sub> or<br>V <sub>IL</sub> , Others =V <sub>IH</sub> /V <sub>IL</sub> |  |  |
| Standby current           |                  | 1            | 1 <sup>*1</sup> | 2    | μΑ   | ~+25°C  | Vin = Vss to Vcc,   |  |  |
|                           | I <sub>SB1</sub> | -            | -               | 3    | μΑ   | ~+40°C  | (1) CS2 ≤ 0.2V or<br>(2) CS1# ≥ Vcc-0.2V,   |  |  |
|                           | ISB1             | -            | -               | 8    | μΑ   | ~+70°C  | CS2 ≥ Vcc-0.2V  |  |  |
|                           |                  | -            | -               | 10   | μА   | ~+85°C  |   |  |  |
| Output high voltage       | V <sub>OH</sub>  | 2.4          | -               | -    | V    | I <sub>OH</sub> = -0.5mA  |   |  |  |
|                           | V <sub>OH2</sub> | Vcc<br>- 0.5 | -               | -    | V    | I <sub>OH</sub> = -0.05mA   |   |  |  |
| Output low voltage        | $V_{OL}$         | -            | -               | 0.4  | V    | I <sub>OL</sub> = 2mA   |   |  |  |

Note 1. Typical parameter indicates the value for the center of distribution at 3.0V (Ta= 25°C), and not 100% tested.

## Capacitance

 $(Vcc = 2.7V \sim 3.6V, f = 1MHz, Ta = -40 \sim +85^{\circ}C)$ 

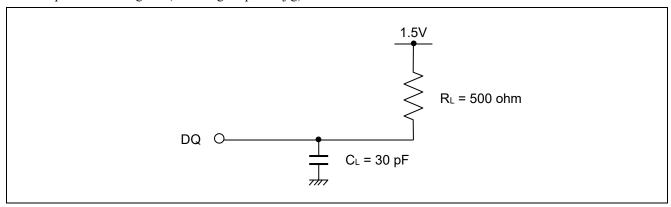
| Parameter                  | Symbol | Min. | Тур. | Max. | Unit | Test conditions | Note |
|----------------------------|--------|------|------|------|------|-----------------|------|
| Input capacitance          | C in   | -    | -    | 8    | pF   | Vin =0V         | 1    |
| Input / output capacitance | C 1/0  | -    | -    | 10   | pF   | VI/O =0V        | 1    |

Note 1. This parameter is sampled and not 100% tested.

### **AC Characteristics**

Test Conditions (Vcc =  $2.7V \sim 3.6V$ , Ta =  $-40 \sim +85$ °C)

- Input pulse levels: VIL = 0.4V, VIH = 2.2V
- Input rise and fall time: 5ns
- Input and output timing reference level: 1.5V
- Output load: See figures (Including scope and jig)



#### **Read Cycle**

| Parameter                          | Symbol            | Min. | Max. | Unit | Note  |
|------------------------------------|-------------------|------|------|------|-------|
| Read cycle time                    | t <sub>RC</sub>   | 55   | -    | ns   |       |
| Address access time                | t <sub>AA</sub>   | -    | 55   | ns   |       |
| Chin palest appear time            | t <sub>ACS1</sub> | -    | 55   | ns   |       |
| Chip select access time            | t <sub>ACS2</sub> | -    | 55   | ns   |       |
| Output enable to output valid      | toe               | -    | 30   | ns   |       |
| Output hold from address change    | tон               | 10   | -    | ns   |       |
| Chin coloct to cutnut in law 7     | t <sub>CLZ1</sub> | 10   | -    | ns   | 2,3   |
| Chip select to output in low-Z     | t <sub>CLZ2</sub> | 10   | -    | ns   | 2,3   |
| Output enable to output in low-Z   | toLZ              | 5    | -    | ns   | 2,3   |
| Chin deceled to output in high 7   | t <sub>CHZ1</sub> | 0    | 20   | ns   | 1,2,3 |
| Chip deselect to output in high-Z  | t <sub>CHZ2</sub> | 0    | 20   | ns   | 1,2,3 |
| Output disable to output in high-Z | tonz              | 0    | 20   | ns   | 1,2,3 |

#### **Write Cycle**

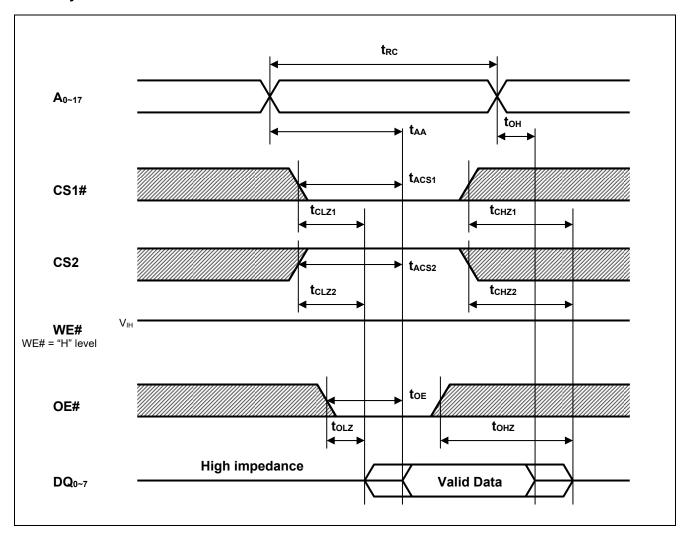
| Parameter                          | Symbol          | Min. | Max. | Unit | Note |
|------------------------------------|-----------------|------|------|------|------|
| Write cycle time                   | twc             | 55   | -    | ns   |      |
| Address valid to end of write      | t <sub>AW</sub> | 50   | -    | ns   |      |
| Chip select to end of write        | tcw             | 50   | -    | ns   | 5    |
| Write pulse width                  | twp             | 45   | -    | ns   | 4    |
| Address setup time                 | t <sub>AS</sub> | 0    | -    | ns   | 6    |
| Write recovery time                | twR             | 0    | -    | ns   | 7    |
| Data to write time overlap         | t <sub>DW</sub> | 25   | -    | ns   |      |
| Data hold from write time          | t₀н             | 0    | -    | ns   |      |
| Output enable from end of write    | tow             | 5    | -    | ns   | 2    |
| Output disable to output in high-Z | tонz            | 0    | 20   | ns   | 1,2  |
| Write to output in high-Z          | twnz            | 0    | 20   | ns   | 1,2  |

#### Note

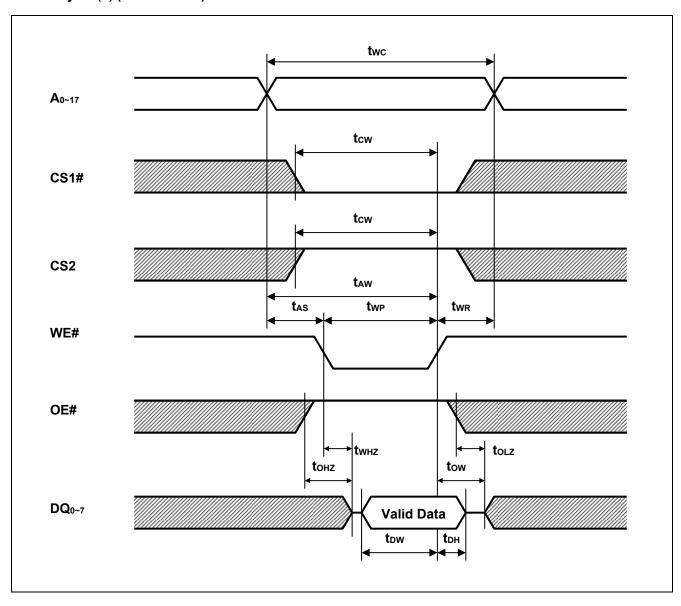
- 1. t<sub>CHZ</sub>, t<sub>OHZ</sub> and t<sub>WHZ</sub> are defined as the time at which the outputs achieve the open circuit conditions and are not referred to output voltage levels.
- 2. This parameter is sampled and not 100% tested.
- 3. At any given temperature and voltage condition,  $t_{HZ}$  max is less than  $t_{LZ}$  min both for a given device and from device to device.
- 4. A write occurs during the overlap of a low CS1#, a high CS2, a low WE#.
  - A write begins at the latest transition among CS1# going low, CS2 going high and WE# going low.
  - A write ends at the earliest transition among CS1# going high, CS2 going low and WE# going high. twp is measured from the beginning of write to the end of write.
- 5. t<sub>CW</sub> is measured from the later of CS1# going low or CS2 going high to end of write.
- 6. tas is measured the address valid to the beginning of write.
- 7. twR is measured from the earliest of CS1# or WE# going high or CS2 going low to the end of write cycle.
- 8. Don't apply inverted phase signal externally when DQ pin is output mode.

# **Timing Waveforms**

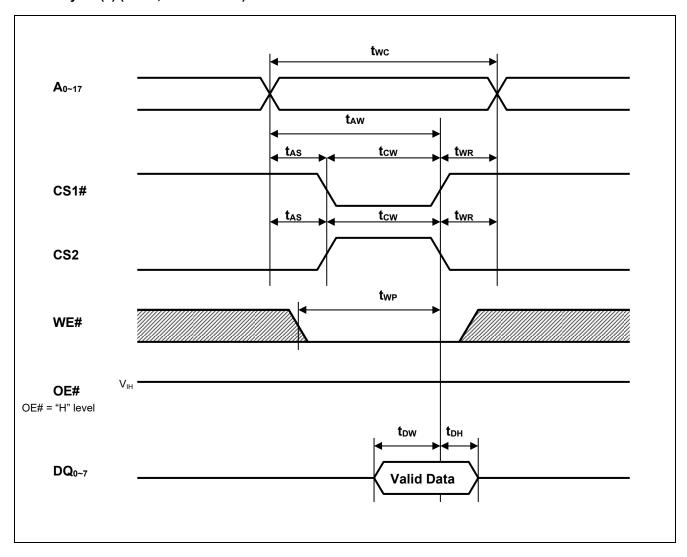
## **Read Cycle**



## Write Cycle (1) (WE# CLOCK)



## Write Cycle (2) (CS1#, CS2 CLOCK)



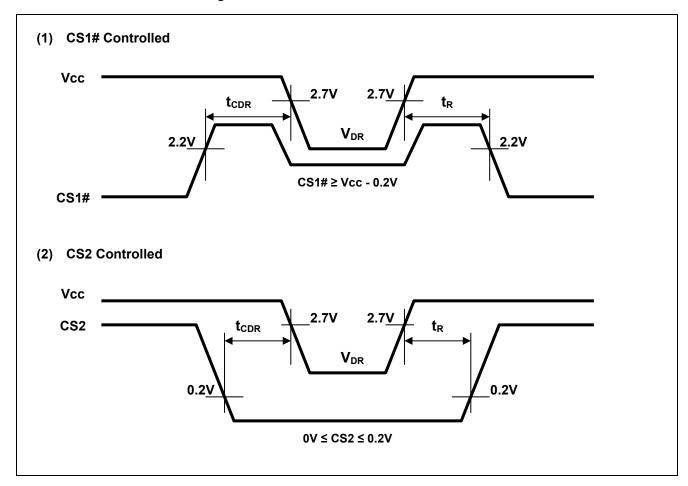
### **Low Vcc Data Retention Characteristics**

| Parameter                            | Symbol          | Min. | Тур.        | Max. | Unit | Test conditions*2   |  |  |
|--------------------------------------|-----------------|------|-------------|------|------|---|--|--|
| V <sub>CC</sub> for data retention   | V <sub>DR</sub> | 2.0  | -           | 3.6  | V    | Vin ≥ 0V,<br>(1) 0V ≤ CS2 ≤ 0.2V or<br>(2) CS1# ≥ Vcc-0.2V,<br>CS2 ≥ Vcc-0.2V |  |  |
| Data retention current               | Iccdr           | -    | <b>1</b> *1 | 2    | μА   | ~+25°C  | Vcc=3.0V, Vin ≥ 0V,                    |  |
|                                      |                 | -    | -           | 3    | μА   | ~+40°C  | (1) 0V ≤ CS2 ≤ 0.2V or                 |  |
|                                      |                 | 1    | 1           | 8    | μА   | ~+70°C  | (2) CS1# ≥ Vcc-0.2V,<br>CS2 ≥ Vcc-0.2V |  |
|                                      |                 | -    | -           | 10   | μА   | ~+85°C  |  |  |
| Chip deselect time to data retention | tcdr            | 0    | -           | -    | ns   | See retention waveform.   |  |  |
| Operation recovery time              | t <sub>R</sub>  | 5    | -           | -    | ms   | See reten   | uon waveionn.                          |  |

Note 1. Typical parameter indicates the value for the center of distribution at 3.0V (Ta= 25°C), and not 100% tested.

2. CS2 controls address buffer, WE# buffer, CS1# buffer, OE# buffer and Din buffer. If CS2 controls data retention mode, Vin levels (address, WE#, CS1#, OE#, DQ) can be in the high impedance state.
If CS1# controls data retention mode, CS2 must be CS2 ≥ Vcc-0.2V or 0V ≤ CS2 ≤ 0.2V. The other input levels (address, WE#, OE#, DQ) can be in the high impedance state.

### **Low Vcc Data Retention Timing Waveforms**



| R1LV0208BSA Data Sheet |
|------------------------|
|                        |

|      |           | Description |  |  |  |  |
|------|-----------|-------------|--|--|--|--|
| Rev. | Date      | Page        | Summary                                  |  |  |  |
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| 1.01 | 2020.2.20 | Last page   | Updated the Notice to the latest version |  |  |  |
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